

Specification

Part No. : **LLP.2500.X.A.30**

Description : LTCC Low Pass Filter for 2500MHz

Bandwidth 100MHz

Features : Cutoff Frequency 2450 MHz

Low Insertion Loss

Low Pass Band Ripple

High Attenuation

Ultra-Compact, Low Profile SMT Package

Dims: 1.6 x 0.8 x 0.6mm







1. Introduction

Taoglas are utilizing their deep understanding of the RF component design and manufacturing process to provide high-quality, small-form-factor, cost-effective and easy to implement RF filters. The Taoglas Filters Division will feature a range of off-the-shelf filters for a variety of applications, including filters for emerging license free bands used for IoT and for GPS L1/L2 and L1/L5 applications. We can also work with customers to develop bespoke filter solutions.

Taoglas LTCC filters are designed to be used in wireless transmitters or receivers. They feature low insertion loss and provide good rejection of unwanted signals at harmonic frequencies for improved system performance. The product is manufactured as a multi-layer monolithic ceramic structure which provides high reliability in a lightweight, low-profile, industrial standard SMT package.

These small part sizes allow for high density PCB layout, provide excellent solderability, and allow for easy visual inspection capability.

The LBP.2500.X.A.30 is a standard Taoglas product but can be customized for specific customer needs. For more information please contact your regional sales office.



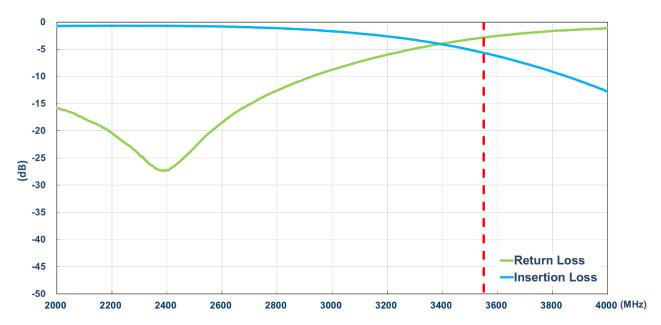
2. Specification

ELECTRICAL			
Cutoff Frequency	2450 MHz		
Insertion Loss	0.42 dB max		
Passband Ripple	0.5 dB max		
Return Loss	< -14 dB		
Attenuation	> 25dB @ 4800 MHz \sim 5000 MHz		
	> 18dB @ 5000 MHz \sim 8000 MHz		
In/Out Impedance	50 Ω		
Power Dissipation	1.0 W min.		
MECHANICAL			
Dimension	1.6 x 0.8 x 0.6mm (L x W x H)		
Material	Ceramic		
Finish	Ag plated		
ENVIRONMENTAL			
Operating Temperature	-40°C to 85°C		
Storage Temperature	-40°C to 85°C		

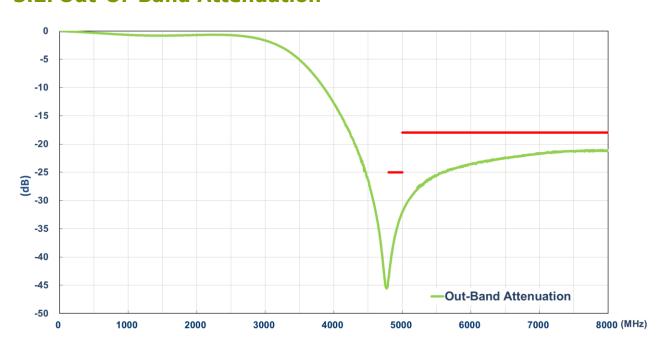


3. Characteristics Curve

3.1. Pass Band Return & Insertion Loss



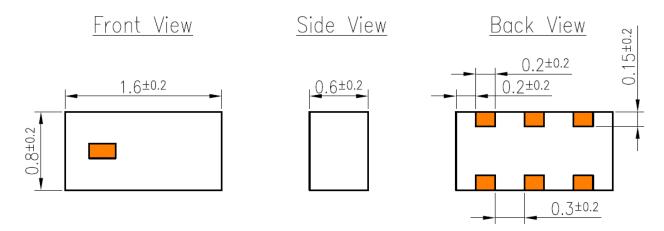
3.2. Out-Of-Band Attenuation





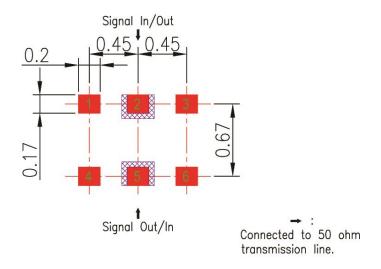
4. Mechanical Drawings (Unit: mm)

4.1. Antenna Drawings

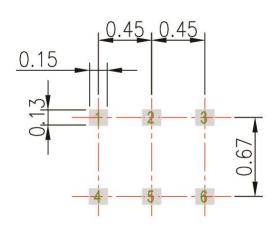




4.2. Recommended PCB Layout 4.2.1. Top Copper



4.2.2. Top Solder Paste

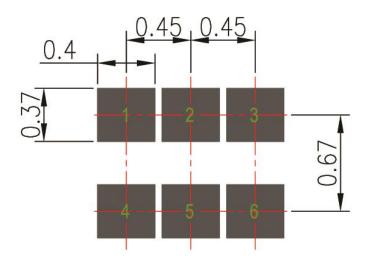


NOTE:

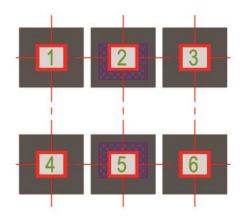
- 1. Ag Plated area
- 2. Solder Mask area
- 3. Copper area
- 4. Paste area
- 5. Copper Keepout Area
- 6. Any vias in pads should be either filled or tented to prevent solder from wicking away from the pad during reflow.
- 7. The dimension tolerances should follow standard PCB manufacturing guidelines



4.2.3. Top Solder Mask



4.2.4. Composite Diagram



NOTE:

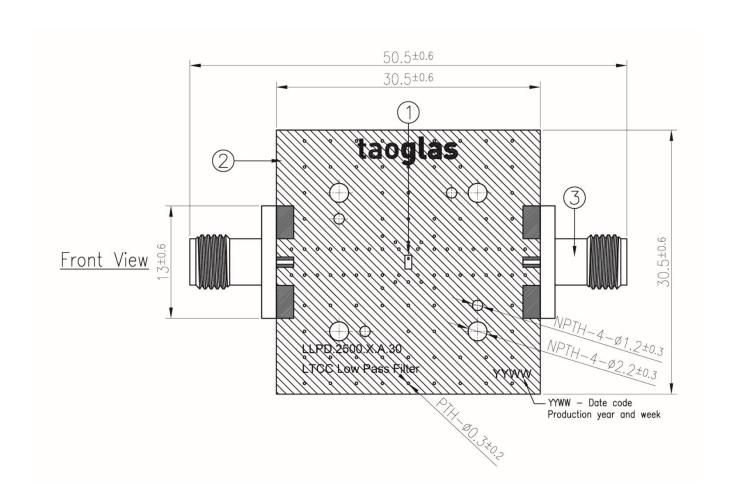
- 1. Ag Plated area
- 2. Solder Mask area
- 3. Copper area
- 4. Paste area
- 5. Copper Keepout Area



- 6. Any vias in pads should be either filled or tented to prevent solder from wicking away from the pad during reflow.
- 7. The dimension tolerances should follow standard PCB manufacturing guidelines



4.3. Evaluation Board

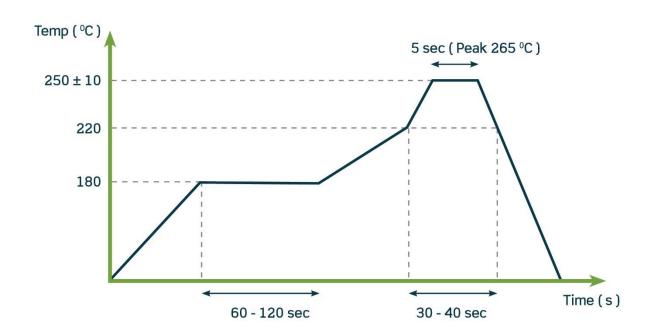


	Name	Material	Finish	QTY
1	Filter (1.6x0.8x0.6mm)	Ceramic	Clear	1
2	PCB	Composite 1.0t	Black	1
3	SMA(F) ST	Brass	Au Plated	2



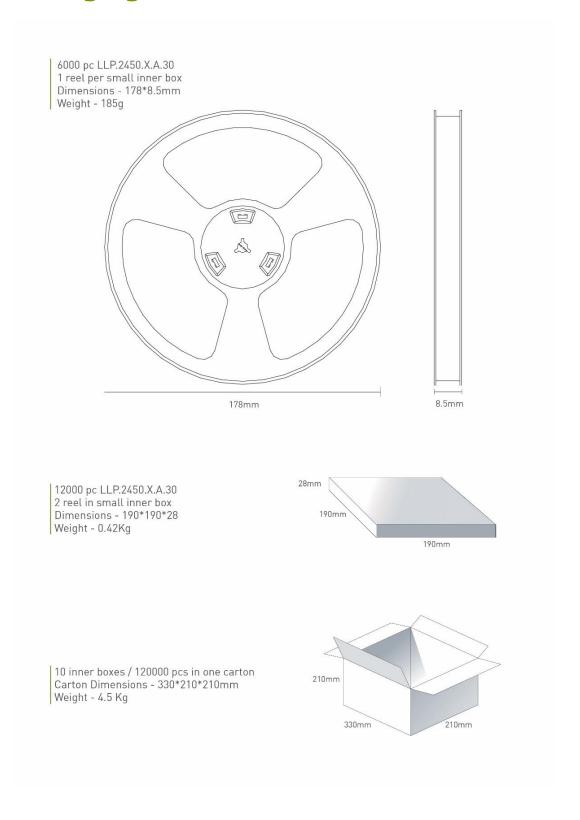
5. Recommended Reflow Soldering Profile

Phase	Profile Features	Maximum
	Temperature Min	150 °C
Preheat	Temperature Max	180 °C
	Duration	60-120 sec
Ramp-Up	Avg. Ramp up rate	3 °C/sec (max)
Doflavy	Temperature	220 °C
Reflow	Duration	30-40 sec
Dools	Temperature	265 °C
Peak	Duration	5 sec Max
Ramp Down	Avg. Ramp down rate	3 °C/sec (max)





6. Packaging





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